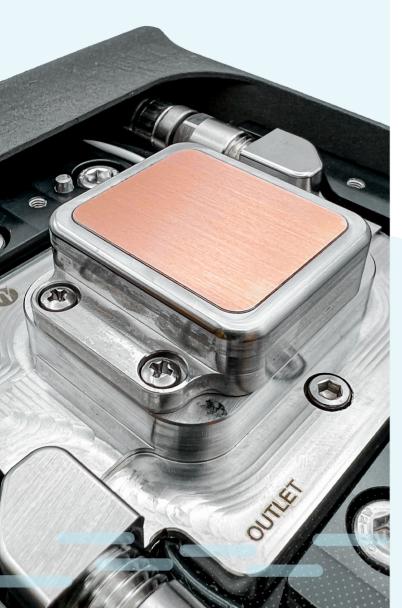
MIKROS TU₃



HEAT | COOL | TEST

ABOUT THE TU3

The TU3 is a thermal test head for semiconductor validation that combines Mikros' patented high-performance microchannel cooling with embedded heaters, precision fluid controls and full mechanical gimbaling to provide tight temperature control of chips during their various stages of testing.

OPTIMIZATION FOR TEST

Originally designed to retrofit into existing automated test equipment (ATE), the TU3 thermal control technology can be customized to a wide variety of test setups. The TU3 provides the highest cooling capacity and fastest thermal transients available on the market today.

KEY FEATURES

- High cooling capacity using microchannel flow paths
- Fast thermal transients using integrated heater designs
- **Easy serviceability** with quick disconnect hoses
- Removeable cold plates for new processors
- User interface for easy performance tracking
- **Durability tested** to 1 million insertions

SYSTEM PERFORMANCE

COOLING CAPACITY	50 W/C-cm ² (for 800W-1kW processors)
THERMAL TRANSIENT	80°C drop in < 2 sec
TEMP RANGE	-20 C ° - 105 Cʻ

SOFTWARE INTERFACE ## Test Head Thermal Recipes

DATA LOGGING	Automatic and manual tracking of thermal data
CONTROL MODES	DUT Temp control
	Cold Plate Temp control
COMPLIANCE	X-Y: 1mm, Tilt: 5° from horizontal



AC REQUIREMENTS

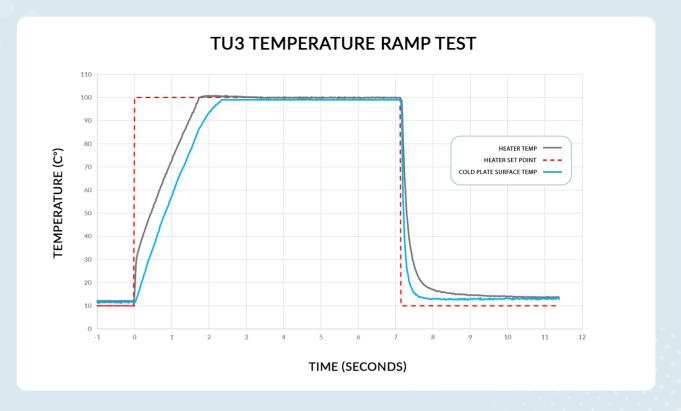
> 120-240 VAC, SINGLE PHASE

PRESSURE/FLOW

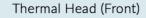
> CHILLER WITH PUMP CAPABLE OF 1.2 LPM @ 40 PSI

CUSTOMIZATION

- > COMMUNICATION
- > USB SERIAL ANALOG IO
- > ADAPTABLE TO A WIDE VARIETY OF HANI DERS









Controller



Thermal Head (Back)

Would you like to implement this into your test system?

Follow us on the web www.mikrostechnologies.com for more information about this sytem. Still have questions and want to learn more? Email us at info@mikros.net.

